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Semiconductor devices –
Integrated circuits –

Part 23-5:
Hybrid integrated circuits and film structures – Manufacturing line certification – Procedure for qualification approval

Dispositifs à semiconducteurs –
Circuits intégrés –

Partie 23-5:
Circuits intégrés hybrides et structures par films –
Certification de la ligne de fabrication –
Procédure d'homologation

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – INTEGRATED CIRCUITS –

Part 23-5: Hybrid integrated circuits and film structures – Manufacturing line certification – Procedure for qualification approval

FOREWORD

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International Standard IEC 60748-23-5 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the European standard EN 165000-5 and the following documents:

FDIS	Report on voting
47A/672/FDIS	47A/677/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

This standard should be read in conjunction with IEC 60748-23-1.

The QC number that appears on the front cover of this publication is the specification number in the IEC Quality Assessment System for Electronic Components (IECQ).

The committee has decided that the contents of this publication will remain unchanged until 2006. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

SEMICONDUCTOR DEVICES – INTEGRATED CIRCUITS –

Part 23-5: Hybrid integrated circuits and film structures – Manufacturing line certification – Procedure for qualification approval

1 Scope

This part of IEC 60748-23 applies to high quality hybrids (with films) incorporating special customer quality and reliability requirements whose quality is assessed on the basis of Qualification Approval.

NOTE 1 Hybrid integrated circuits may be fully or part completed. Part completed devices are those that may be supplied to customers for further processing.

NOTE 2 Test methods are selected from IEC 60748-23-1. A blank detail specification (BDS) is included to assist manufacturers and users in the preparation of detail specifications.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60748-23-1:2002, *Semiconductor devices – Integrated circuits – Part 23-1: Hybrid integrated circuits and film structures – Manufacturing line certification – Generic specification*

IEC 61340-5-1:1998, *Electrostatics – Part 5-1: Protection of electronic devices from electro-static phenomena – General requirements*

QC 001002-3:1998, *IEC Quality Assessment System for Electronic Components (IECQ) – Rules of Procedure – Part 3: Approval procedures*